

**Description**

The SX280N04T uses advanced technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

**General Features**

$V_{DS} = 40V$   $I_D = 280A$

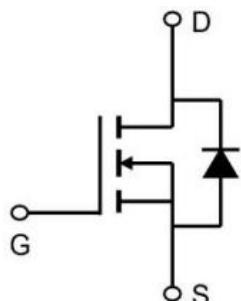
$R_{DS(ON)} < 1.5m\Omega$  @  $V_{GS}=10V$

**Application**

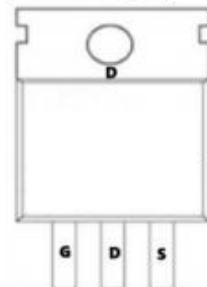
BMS

BLDC

UPS



TO-263-3L

**Absolute Maximum Ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Max.	Units
VDSS	Drain-Source Voltage	40	V
VGSS	Gate-Source Voltage	$\pm 20$	V
ID@TC=25°C	Continuous Drain Current, VGS @ 10V1	280	A
ID@TC=100°C	Continuous Drain Current, VGS @ 10V1	200	A
IDM	Pulsed Drain Current	1120	A
EAS	Single Pulsed Avalanche Energy	818	mJ
IAS	Avalanche Current	70	A
PD@TC=25°C	Power Dissipation	230	W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	60	°C/W
R <sub>θJC</sub>	Thermal Resistance, Junction to Case	1.5	°C/W
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C

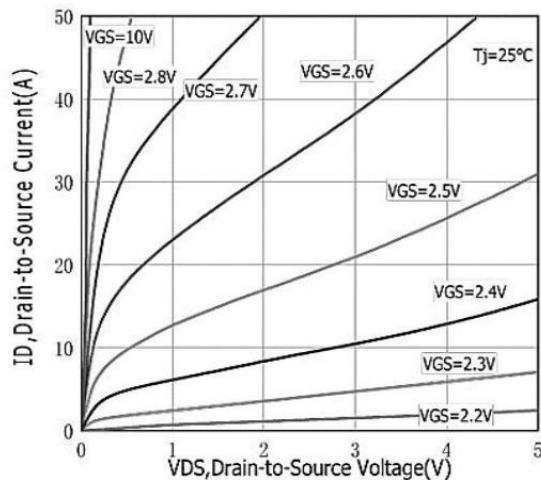
**MOSFET N-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	40	48	-	V
IDSS	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}, V_{GS}=0\text{V},$	-	-	1.0	$\mu\text{A}$
IGSS	Gate to Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}= \pm 20\text{V}$	-	-	$\pm 100$	nA
VGS(th)	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.8	2.5	V
RDS(on)	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}, I_D=30\text{A}$	-	1.2	1.5	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=20\text{A}$	-	1.7	2.5	$\text{m}\Omega$
Ciss	Input Capacitance	$V_{DS}=20\text{V}, V_{GS}=0\text{V}, f=1.0\text{MHz}$	-	8300	-	pF
Coss	Output Capacitance		-	1510	-	pF
Crss	Reverse Transfer Capacitance		-	130	-	pF
Qg	Total Gate Charge	$V_{DS}=20\text{V}, I_D=85\text{A}, V_{GS}=10\text{V}$	-	127	-	nC
Qgs	Gate-Source Charge		-	35	-	nC
Qgd	Gate-Drain("Miller") Charge		-	26	-	nC
td(on)	Turn-on Delay Time	$V_{DD}=20\text{V}, I_D=85\text{A}, R_G=1.6\Omega, V_{GS}=10\text{V}$	-	22.5	-	ns
tr	Turn-on Rise Time		-	6.7	-	ns
td(off)	Turn-off Delay Time		-	80.3	-	ns
tf	Turn-off Fall Time		-	26.9	-	ns
IS	Maximum Continuous Drain to Source Diode Forward Current		-	-	300	A
ISM	Maximum Pulsed Drain to Source Diode Forward Current		-	-	750	A
VSD	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}, I_S=30\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$T_J=25^\circ\text{C}, I_F=I_S, dI/dt=100\text{A}/\mu\text{s}$	-	100	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	163	-	nC

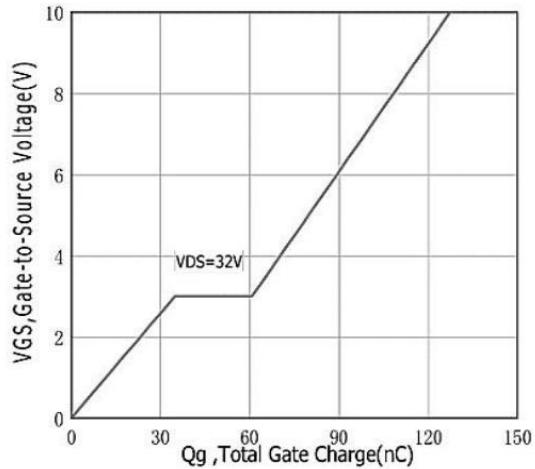
**Note :**

1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{DD} =32\text{V}, V_{GS} =10\text{V}, L=0.1\text{mH}, I_{AS} =70\text{A}$
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

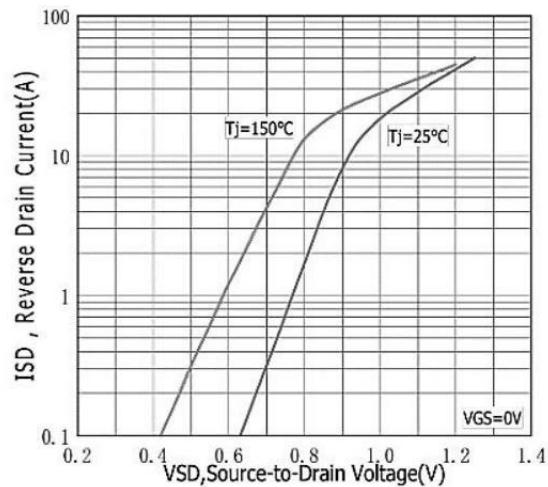
## Typical Characteristics



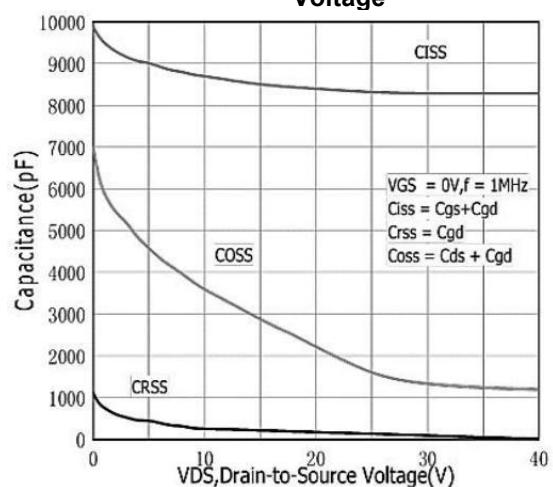
**Figure 1 Typical Output Characteristics**



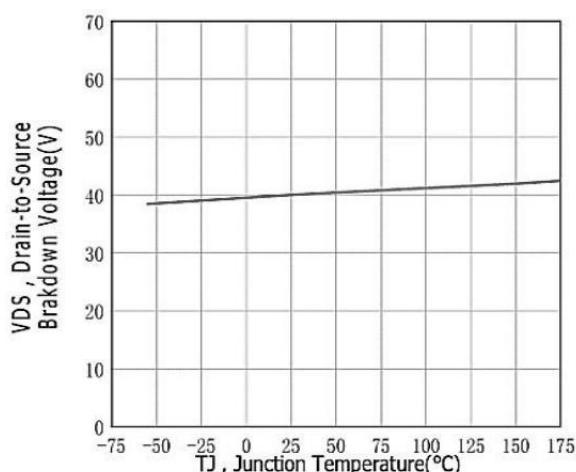
**Figure 2 Typical Gate Charge vs Gate to Source Voltage**



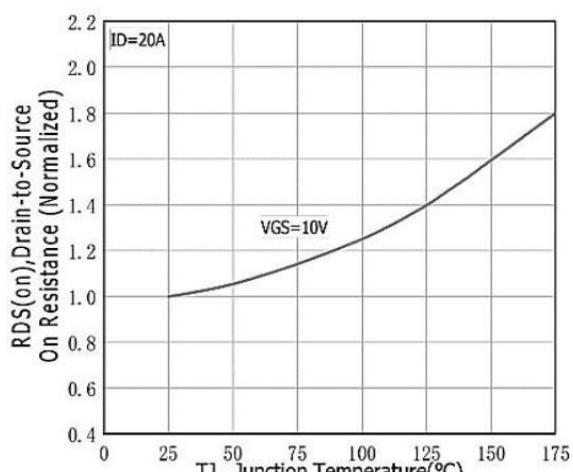
**Figure 3 Typical Body Diode Transfer Characteristics**



**Figure 4: Body Diode Characteristics**

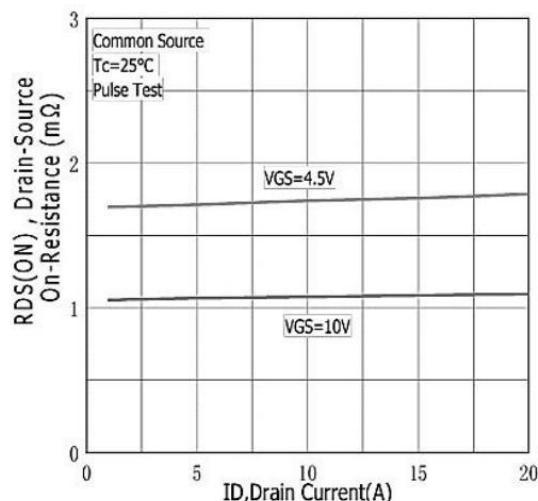


**Figure 5 Typical Breakdown Voltage vs Junction Temperature**

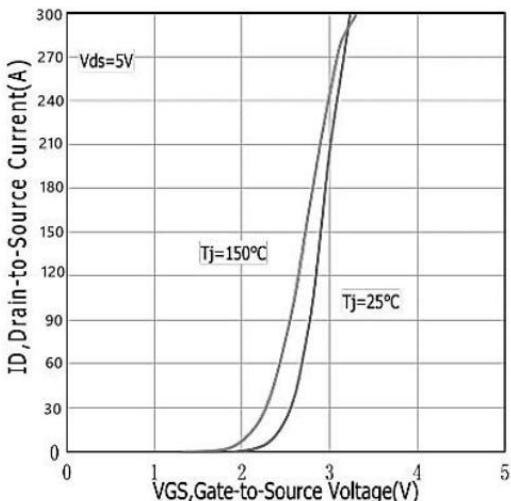


**Figure 6: Capacitance Characteristics**

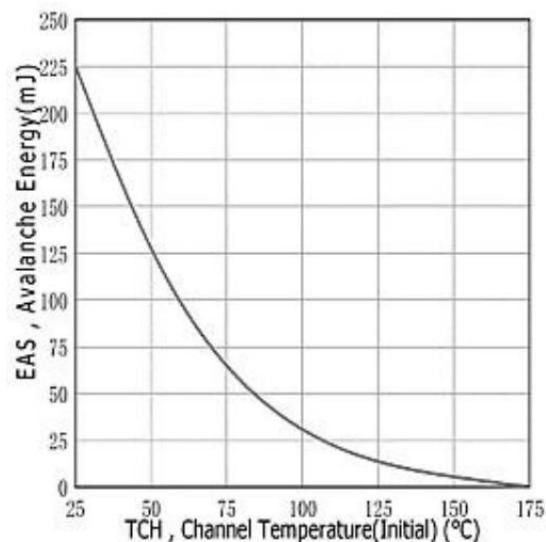
## Typical Characteristics



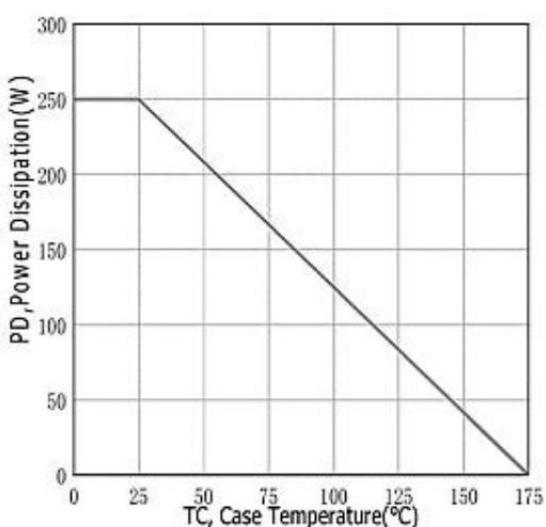
**Figure.7 Typical Drain to Source ON Resistance vs Drain Current**



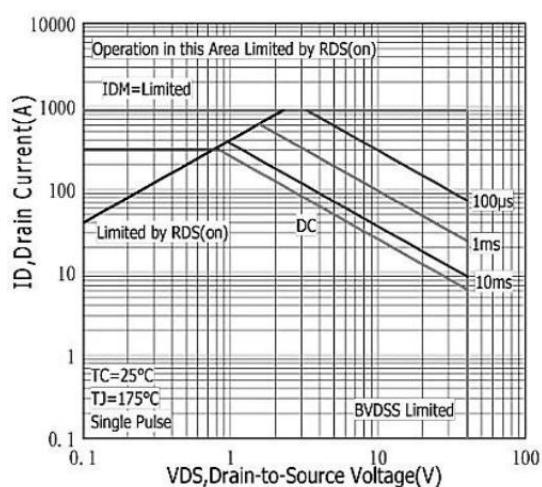
**Figure.10 Typical Transfer Characteristics**



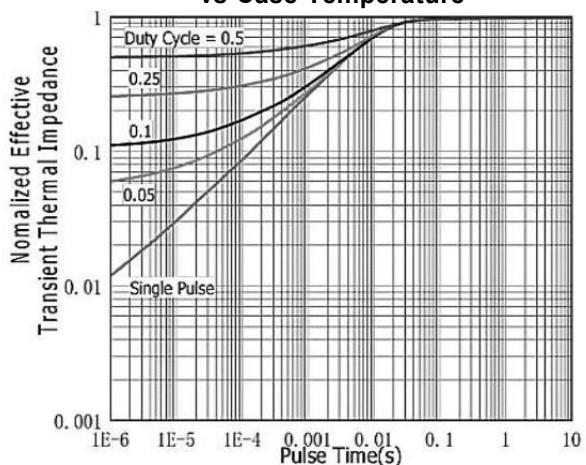
**Figure.9 Maximum EAS vs Channel Temperature**



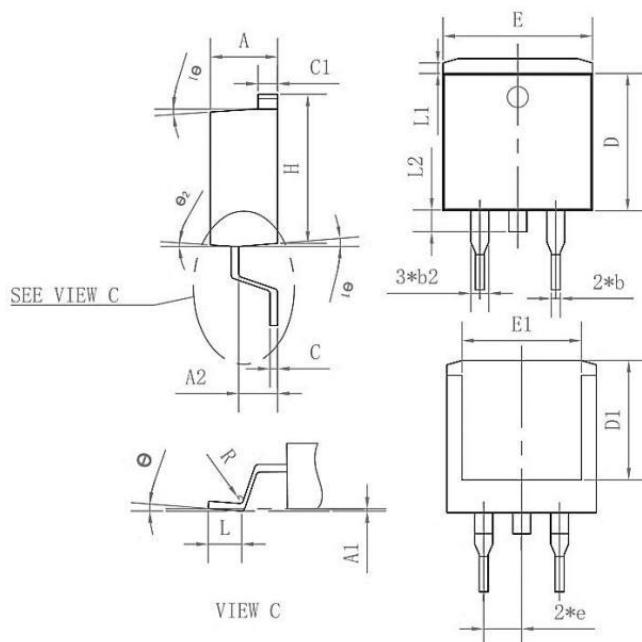
**Figure.12 Maximum Power Dissipation vs Case Temperature**



**Figure 11: Maximum Safe Operating Area**



**Figure.12: Maximum Effective Transient Thermal Impedance, Junction-to-Cas**

**MOSFET Package Mechanical Data-TO-263-3L-SLK**

Symbol	Common		
	Mim	Nom	Max
A	4.35	4.47	4.60
A1	0.09	0.10	0.11
A2	2.30	2.40	2.70
b	0.70	0.80	1.00
b2	1.25	1.36	1.50
C	0.45	0.50	0.65
C1	1.29	1.30	9.40
D	9.10	9.20	9.30
D1	7.90	8.00	8.10
E	9.85	10.00	10.20
E1	7.90	8.00	8.10
H	15.30	15.50	15.70
e	-	2.54	-
L	2.34	2.54	2.74
L1	1.00	1.10	1.20
L2	1.30	1.40	1.50
R	0.24	0.25	0.26
θ	0°	4°	8°
θ1	4°	7°	10°
θ2	0°	3°	6°

**Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-263-3L		800